



Electronic Packaging: Design, Materials, Process, and Reliability

John H. Lau, C.P. Wong, J.L. Prince

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The ultimate, up-to-the-minute electronic packaging resource

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For the first time, four well-known experts representing the four relevant fields--mechanical engineering, electrical engineering, thermal management, and materials--team up to provide a single-volume comprehensive reference that explains packaging and interconnection basics, details design tradeoff considerations, and presents specific system-level solutions. This unprecedented and unsurpassed multi-disciplinary coverage not only includes all the new technologies--BGA, Flip Chip, DCA, and CSP--it shows how they can be most effectively integrated.

With its clear explication of both theoretical and practical issues, *Electronic Packaging* will be of considerable and continuing value if you hope to design and/or refine more reliable, robust, and cost-effective packaging solutions for virtually any interconnect system.

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